



Product Change Notification - KSRA-07LEDG378 [\(Printer Friendly\)](#)

Date:

25 Jan 2018

Product Category:

Linear Op Amps; 8-bit PIC Microcontrollers; Interface- Passive-Keyless-Entry Analog Front End; Touch Controllers; Interface- Infrared Products; USB Bridge; Interface- Controller Area Network (CAN); Successive Approximation Register (SAR) A/D Converters; Sigma - Delta A/D Converters; Digital Potentiometers; System D/A Converters; Linear Comparators; Linear Selectable Gain Amplifiers; Linear Programmable Gain Amplifiers; Memory; Power MOSFET Drivers; Interface- LIN Transceiver; Ionization Smoke Detector Front Ends; Piezoelectric Horn Drivers; Charge Pump DC-to-DC Converters

Notification subject:

CCB 3140 and CCB 3140.001 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products available in 8L and 14L SOIC package at MTAI assembly site.

Notification text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products available in 8L and 14L SOIC package at MTAI assembly site.

Pre Change:

Using Palladium coated copper wire (PdCu) bond wire



Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (HQ) / MTAI	Microchip Technology Thailand (HQ) / MTAI
Wire material	PdCu Wire	CuPdAu Wire
Die attach material	8390A	8390A
Molding compound material	G600V	G600V
Lead frame material	CDA194	CDA194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 22, 2018 (date code: 1808)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	January 2018				February 2018			
	01	02	03	04	05	06	07	08
Qual Report Availability				X				
Final PCN Issue Date				X				
Estimated								X

Implementation Date									
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Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

January 25, 2018: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-07LEDG378_Affected_CPN.pdf](#)

[PCN_KSRA-07LEDG378_Qual_Report.pdf](#)

[PCN_KSRA-07LEDG378_Affected_CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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